2SC5926

Silicon NPN triple diffusion planar type

For power amplification

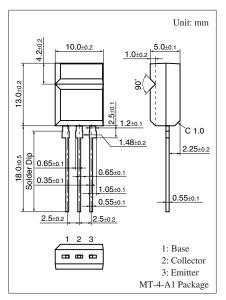
■ Features

- High forward current transfer ratio h_{FE} which has satisfactory linearity.
- Low collector-emitter saturation voltage V_{CE(sat)}
- Allowing supply with the radial taping

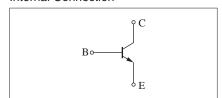
■ Absolute Maximum Ratings $T_C = 25$ °C

Parameter	Symbol	Rating	Unit	
Collector-base voltage (Emitter open)	V _{CBO}	80	V	
Collector-emitter voltage (Base open)	V _{CEO}	60	V	
Emitter-base voltage (Collector open)	V_{EBO}	6	V	
Collector current	I_C	3	A	
Peak collector current	I_{CP}	6	A	
Collector power dissipation	P _C	15	W	
$T_a = 25^{\circ}C$		2.0		
Junction temperature	T_{j}	150	°C	
Storage temperature	T _{stg}	-55 to +150	°C	

Note) *: Non-repetitive peak collector current



Internal Connection



■ Electrical Characteristics $T_C = 25$ °C ± 3 °C

Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Collector-emitter voltage (Base open)	V _{CEO}	$I_C = 10 \text{ mA}, I_B = 0$	60			V
Collector-base cutoff current (Emitter open)	I_{CBO}	$V_{CB} = 80 \text{ V}, I_{E} = 0$			100	μΑ
Collector-emitter cutoff current (Base open)	I_{CEO}	$V_{CE} = 40 \text{ V}, I_{B} = 0$			100	μΑ
Emitter-base cutoff current (Collector open)	I_{EBO}	$V_{EB} = 6 \text{ V}, I_{C} = 0$			100	μΑ
Forward current transfer ratio *1	h _{FE1} *2	$V_{CE} = 4 \text{ V}, I_{C} = 0.5 \text{ A}$	500		2 300	_
	h _{FE2}	$V_{CE} = 4 \text{ V}, I_{C} = 3 \text{ A}$	100			
Collector-emitter saturation voltage	V _{CE(sat)}	$I_C = 1 \text{ A}, I_B = 20 \text{ mA}$			0.7	V
Turn-on time	t _{on}	I _C = 1 A, Resistance loaded	0.2			μs
Storage time	t _{stg}	$I_{B1} = 0.1 \text{ A}, I_{B2} = -0.1 \text{ A}$	1.5			μs
Fall time	t _f	$V_{CC} = 50 \text{ V}$	0.1			μs

Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7030 measuring methods for transistors.

2. *1: Pulse measurement

*2: Rank classification

Rank	Q	Р
h _{FE1}	500 to 1 500	1300 to 2300

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